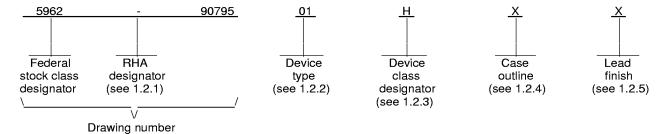
						F	REVIS	IONS										
LTR		DESCRIPTION								DATE (YR-MO-DA)		MO-DA) APPROVED		)				
Α	Make chan	ges to table	e I. Re	ewrite e	entire o	docum	ent.					94-0	1-18		K. A. Cottongim			
В	Add device	types 03 a	and 04.									99-0	6-28		K	(. A. Cc	ottong	im
	THE O	RIGINA	L FIR	RST F	PAGE	E OF	THIS	S DR	AWI	NG I	HAS	BEE	N RI	EPL#	ACEL	)		
DEV	THE O	RIGINA	L FIR	RST F	PAGE	E OF	THIS	S DR	AWI	NG F	HAS	BEE	N RI	EPLA	ACED	) 		
	THE O	RIGINA	L FIR	RST F	PAGE	E OF	THIS	S DR	AWI	NG F	HAS	BEE	N RI	EPL#	\CE[	) 		
SHEET	THE O	RIGINA	L FIR	RST F	PAGE	€ OF	THIS	S DR	AWI	NG I	HAS	BEE	N RI	EPL#	ACEL	)		
SHEET	THE O	RIGINA	L FIR	RST F	PAGE	€ OF	THIS	S DR	AWI	NG I	HAS	BEE	N RI	EPL#	ACEL	)		
SHEET REV SHEET REV STATU	JS	RIGINA		RST F	PAGE	E OF	THIS	S DR	AWI	NG H	HAS	BEE	N RI	EPLA B	\CEL			
SHEET REV SHEET REV STATU	JS	RE		RST F											ACED			
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A	JS S	RE SH	EV	D BY	В	В	В	В	B 5	В 6	8 7	B 8 <b>VPPL</b> '	B 9 Y CEN	B 10	COLUM	MBUS		
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA MICRO	JSSS	RE SH PRE Ga	EV EET	D BY	B 1	В	В	В	B 5	В 6	8 7	B 8 <b>VPPL</b> '	B 9 Y CEN	B 10	COLUM	MBUS		
SHEET REV SHEET REV STATUOF SHEETS PMIC N/A STA MICRO DR. THIS DRAW FOR 1	JS S S S S S S S S S S S S S S S S S S	RE SH PRE Ga CHE Ro	EPAREI Zahr	D BY BY . Heber	B 1	В	В	B 4	B 5	B 6 DEFEN	B 7 ISE SI	B 8 P. O MBUS	B 9 Y CEN O, BOX O, OHIC	B 10 TER (3990) 432	COLUM	MBUS	ЭH	
MICRO DR. THIS DRAW FOR I DEP/ AND AGE	JS S S S S S S S S S S S S S S S S S S	RE SH PRE Ga CHE RO APE Wi	EV IEET EPAREI ECKED bebert M	D BY . Heber D BY . Heckm	B 1	B 2	В	B 4	B 5 ROCI	B 6 DEFEN C	B 7 ISE SI	B 8 P. O MBUS YBRII	B 9 Y CEN O, BOX O, OHIC	B 10 TER (3990 ) 432	16-500	MBUS		

DSCC FORM 2233
APR 97
DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E304-99

## 1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents five product assurance classes, class D (lowest reliability), class E, (exceptions), class G (lowest high reliability), class H (high reliability), and class K, (highest reliability) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.
  - 1.2 <u>PIN</u>. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes H and K RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
  - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function	Maximun linearity error
01	HS9576S/B BIP	16-bit A/D converter, bipolar	±0.006% FSR
02	HS9576T/B BIP	16-bit A/D converter, bipolar	±0.003% FSR
03	HS9576S/B UNI	16-bit A/D converter, unipolar	±0.006% FSR
04	HS9576T/B UNI	16-bit A/D converter, unipolar	±0.003% FSR

1.2.3 <u>Device class designator</u>. This device class designator shall be a single letter identifying the product assurance level as follows:

Device class

Device performance documentation

D, E, G, H or K

Certification and qualification to MIL-PRF-38534

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
X	See figure 1	32	Dual-in-line

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

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## 1.3 Absolute maximum ratings. 1/

0 V dc to +16 V dc 0 V dc to -16 V dc Logic supply voltage range (V<sub>DD</sub>) Analog ground to logic ground -0.5 V dc to +7.0 V dc 0.5 V dc Logic inputs to logic ground ...... 0 V dc to +6.5 V dc Analog inputs to analog ground ..... 0 V dc to +16.5 V dc Voltage on logic outputs ..... 0 V dc to 7.0 V dc 2.0 W 40° C/W +300°C -65°C to +150°C +170°C 

#### 1.4 Recommended operating conditions.

## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbook.</u> The following specification, standards, and handbook form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

#### **SPECIFICATION**

## DEPARTMENT OF DEFENSE

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

## **STANDARDS**

## DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-973 - Configuration Management.

MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.

## **HANDBOOK**

## DEPARTMENT OF DEFENSE

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbook are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

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## 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for applicable device class. Therefore, the tests and inspections herein may not be performed for applicable device class (see MIL-PRF-38534). Futhermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class. The modification in the QM plan shall not affect the form, fit, or function as described herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.
  - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
  - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking of device(s)</u>. Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked as listed in QML-38534.
- 3.6 <u>Data</u>. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

## 4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.
  - 4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:
    - a. Burn-in test, method 1015 of MIL-STD-883.
      - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
      - (2) TA as specified in accordance with table I of method 1015 of MIL-STD-883.
    - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE I. Electrical performance characteristics.							
Test	Symbol	Conditions 1/	Group A	Device	Lir	mits	Unit
		-55°C_ <t<sub>C ≤ +125°C unless otherwise specified</t<sub>	subgroups	type	Min	Max	
Input voltage	V <sub>IN</sub>	Bipolar	1, 2, 3	01, 02	-2.5	+2.5	V
					-5.0	+5.0	]
					-10.0	+10.0	
		Unipolar		03, 04	0	+5.0	
					0	+10.0	
					0	+20.0	
High level input voltage	V <sub>IH</sub>		1, 2, 3	All	2.0		V
Low level input voltage	V <sub>IL</sub>		1, 2, 3	All		0.8	V
High level output voltage	V <sub>OH</sub>		1, 2, 3	All	2.4		V
Low level output voltage	V <sub>OL</sub>		1, 2, 3	All		0.40	V
Supply currents	lcc	V <sub>CC</sub> = +15.45 V dc	1, 2, 3	All		+23	mA
	IEE	V <sub>EE</sub> = -15.45 V dc				-38	
	l <sub>DD</sub>	V <sub>DD</sub> = +5.25 V dc				+37	
Integral linearity error	ILE	End point definition,	4	01, 03	-0.006	+0.006	%FSR
		T <sub>C</sub> = +25°C		02, 04	-0.003	+0.003	
		T <sub>C</sub> = +125°C	5	01, 03	-0.036	+0.036	
				02, 04	-0.023	+0.023	
		T <sub>C</sub> = -55°C	6	01, 03	-0.030	+0.030	
				02, 04	-0.019	+0.019	
Differential linearity error	D <sub>LE</sub>	T <sub>C</sub> = +25°C	4	All	-0.006	+0.006	%FSR
		T <sub>C</sub> = +125°C	5	01, 03	-0.006	+0.046	
				02, 04	-0.006	+0.026	
		T <sub>C</sub> = -55°C	6	01, 03	-0.006	+0.038	
				02, 04	-0.006	+0.022	

See footnotes at end of table.

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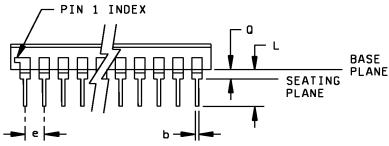
TABLE I. Electrical performance characteristics.							
Test	Symbol	Conditions 1/	Group A	Device	Lir	mits	Unit
		$-55^{\circ}\text{C} \leq \text{T}_{\text{C}} \leq +125^{\circ}\text{C}$ unless otherwise specified	subgroups	type	Min	Max	
Gain error	AE	Adjustable to zero, T <sub>C</sub> = +25°C	4	All	-0.2	+0.2	%FSR
		T <sub>C</sub> = +125°C	5	] '	-0.35	+0.35	
		T <sub>C</sub> = -55°C	6	<u>]                                    </u>	-0.32	+0.32	
Offset error	OE	Bipolar (adjustable to zero), T <sub>C</sub> = +25°C	4	01, 02	-0.2	+0.2	%FSR
		Bipolar (adjustable to zero), T <sub>C</sub> = -55°C, +125°C	5, 6		-0.30	+0.30	
		Unipolar (adjustable to zero), T <sub>C</sub> = +25°C	4	03, 04	-0.1	+0.1	
		Unipolar (adjustable to zero), T <sub>C</sub> = -55°C, +125°C	5, 6		-0.125	+0.125	
Noise at transitions (3 sigma) <u>2</u> /		Peak to peak	4, 5, 6	All		+0.003	%FSR
12-bit conversion time	t <sub>con</sub>	Pin 32 to pin 13, 9, 10, 11 All 12-bit accurate		All		13	μѕ
14-bit conversion time	t <sub>con</sub>	Pin 32 to pin 15, 14-bit accurate	9, 10, 11	All		15	μѕ
16-bit conversion time	t <sub>con</sub>	Pin 32 open, 16-bit accurate	9, 10, 11	All		17	μѕ

 $<sup>\</sup>underline{1}$ / Unless otherwise specified,  $V_{CC}$  = +14.55 V dc to +15.45 V dc,  $V_{EE}$  = -14.55 V dc to -15.45 V dc, and  $V_{DD}$  = +4.75 V dc to +5.25 V dc.

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<sup>2/</sup> Parameter shall be tested as part of device initial chacterization and after design and process changes. Parameter shall be guaranteed to the limits specified in table I for all lots not specifically tested.

# 



			Inches		
Symbol	Millim	neters	Inc	nes	
	Min	Max	Min	Max	
Α		4.90		0.193	
b	0.41	0.51	0.016	0.020	
С	0.23	0.30	0.009	0.012	
D		43.69		1.720	
E		27.94		1.100	
е	2.54	TYP	0.100 TYP		
eA	22.61	23.11	0.890	0.910	
L	5.21		0.205		
Q	0.38	0.89	0.015	0.035	

## NOTES:

- The U. S. preferred system of measurement is the metric SI. This case outline was originally designed using inchpound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound shall take precedence.
- 2. Unless otherwise specified, tolerance is ±.005 (0.13 mm).
- 3. Pin numbers are for reference only.

FIGURE 1. Case outline(s).

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Device types	All		
Case outline	X		
Terminal number	Terminal symbol	Terminal number	Terminal symbol
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16	Bit 1 (MSB)	17 18 19 20 21 22 23 24 25 26 (see note 1) 27 28 29 30 31 32	Serial out Status Digital ground Clock out -15 V (VEE) Analog ground Clock rate control 20 V input 10 V input Bipolar offset Comparator input +15 V (VCC) Gain adjust +5 V (VDD) Convert command Short cycle

## NOTE:

1. Device types 03 and 04, pin 26 is a no connect.

FIGURE 2. <u>Terminal connections</u>.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	
Final electrical parameters	1*,2,3,4,5,6,9,10,11
Group A test requirements	1,2,3,4,5,6,9,10,11
Group C end-point electrical parameters	1,2,3,4
MIL-STD-883, group E end-point electrical parameters for RHA devices	Subgroups** (in accordance with method 5005, group A test table)

- \* PDA applies to subgroup 1.
- \*\* When applicable to this standard microcircuit drawing, the subgroups shall be defined.
- 4.3 <u>Conformance and periodic inspections</u>. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.
  - 4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 7 and 8 shall be omitted.
  - 4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.
  - 4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test, method 1005 of MIL-STD-883.
      - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
      - (2)  $T_A$  as specified in accordance with table I of method 1005 of MIL-STD-883.
      - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
  - 4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.

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- 4.3.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes H and K shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.
  - a. RHA tests for device classes H and K for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
  - b. End-point electrical parameters shall be as specified in table II herein.
  - c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
  - d. For device classes H and K, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at T<sub>A</sub> = +25°C ±5 percent, after exposure.
  - e. Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
  - f. For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
  - g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.
  - 5. PACKAGING
  - 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.
  - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-7603.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, P. O. Box 3990, Columbus, Ohio 43216-5000, or telephone (614) 692-0676.
- 6.6 <u>Sources of supply</u>. Sources of supply are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

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## STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 99-06-28

Approved sources of supply for SMD 5962-90795 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of QML-38534.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9079501HXC	33256	HS9576S/B BIP
5962-9079501HXA	33256	HS9576S/B BIP
5962-9079502HXC	33256	HS9576T/B BIP
5962-9079502HXA	33256	HS9576T/B BIP
5962-9079503HXC	33256	HS9576S/B UNI
5962-9079503HXA	33256	HS9576S/B UNI
5962-9079504HXC	33256	HS9576T/B UNI
5962-9079504HXA	33256	HS9576T/B UNI

- 1/ The lead finish shown for each PIN, representing a hermetic package, is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE <u>number</u>

33256

Vendor name and address

Sipex Corporation 22 Linnell Circle Billerica, MA 01821-3985

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.